





LABORATOIRE BOURGUIGNON DES MATÉRIAUX ET PROCÉDÉS



High speed imaging planing experiment synchronized with multiphysical measurements

Rémi CURTI, Bertrand MARCON



Chipper canter milling: context



Usinage et fragmentation d'une dosse [Kuljich 2016]





 $3D \rightarrow 2D$





Experimental setup



Telecentric objectives (Mitutoyo)

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ET METIERS

R. CURTI / B. MARCON

Up to 12 spots LEDs and guides

Experimental setup







Details about the signals synchronization strategy





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DEMONSTRATION



Oriented fiber composed materials: Wood, CFRP...

BeechGreen state Vc 120 m/min

h 10 mm B 5 mm



Cutting forces measurement



→ Dynamic compensation



Digital Image Correlation CorreliQ4

GOAL: Observe and validate a DEM for the serration of the chip (GranOO)





La<mark>Bo</mark>Ma

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Effective grain direction assessment

Hypothèse : empilements des rayons ligneux et fibres alignés







120

Other applications of the technique



Burr formation in Aluminum alloy machining



Surface Integrity characterization



DES MATÉRIAUX ET PRO

A novel solution to assess the forces in HSM

[2017 Baizeau T. et al]



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Influence of microstruture on machining properties

Titanium alloy with only beta phase (obtain by dedicated heat treatment) Cutting thickness $h = 100 \mu m$ Cutting width b = 3 mmCutting speed Vc = 10 m/min



Photron	 FASTCAM SA-Z type 2100K-M-6 1/50000 sec image : 10937 Time : 17:45 	1024 x 512 +273.425 ms	40000 i/s Début Date : 2018/6/12





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EBSD Analyse







Another Ultra Hight Speed observation media



Even more accurate experimental set-up to obtain very accurate DIC strain fields



Another Ultra Hight Speed observation media



Orthogonal cutting of steel at 1 m/s Lighting: double pulse Nd:Yag laser Imager: sCMOS double frame camera

sCMOS LaVision Camera + pulse Nd:Yag Laser

